

The MJ06 Series is a high-speed signal connector for differential transmission, compatible with backplane/midplane type devices. It has superior high-speed transmission performance, with a balanced transmission structure that is ideal for differential transmission and allows for a simplified mounting pattern design.

Features

■ Compatible with IEC61076-4-101 mounting dimensions. Usage is possible with the same standard connectors (known as HM connectors).

- Pair signal alignment (side pair, 1.8mm pitch) and ground structure, optimized for highspeed differential transmission
- Symmetrical pin structure prevents skew between differential signal pair.
- Press-fit attachment to board for both pin side and socket side connector (finished diameter compatible with 0.6mm dia.)
- Through-hole location to optimize board wiring pattern.
- Compatible with connector height 9mm max. from board, minimum slot distance 17mm.
- Available in cable connection type. (Please contact us for more information.)

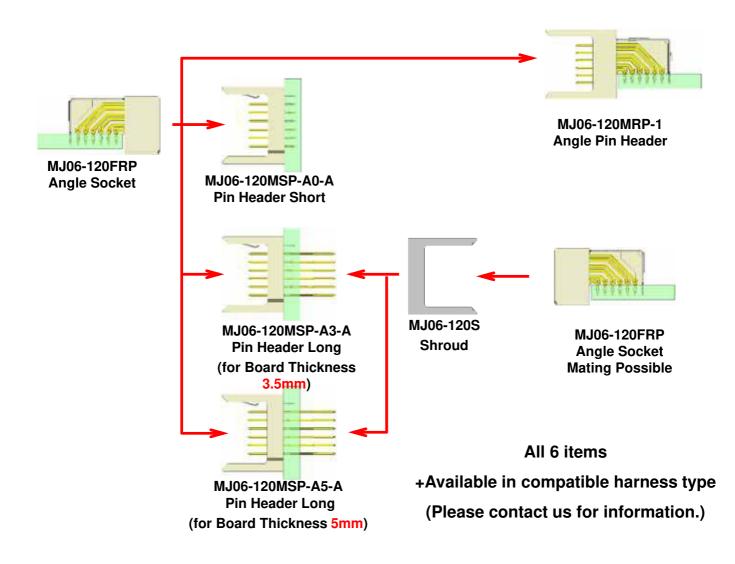
Applications

■ Factory automation equipment, semiconductor manufacturing equipment, various inspection and measuring devices, server/storage devices, communication/network devices, broadcasting equipment, medical equipment, etc.

General Specifications

- No. of Contacts: 120 pos. (signal + ground / module)
- Differential Impedance: $100\Omega \pm 15\Omega$ (Tr=100ps [10-90%])
- Crosstalk: 5% max. (Tr=100ps [10-90%])
- Rated Voltage: AC200 Vr.m.s
- Rated Current: 1A
- Operating Temperature: -35 to 85 Deg. C
- Compliant Pin: single insertion force 100N max. / single retention force 10N min. (after test)
- Applicable Board Thickness: 1.4mm to 5.0mm

MJ06 Series Mating Operation



Materials and Finishes

■ P	Pin Connector						
C	omponent	Material / Finish					
In	sulator	Glass filled PBT (white)					
C	ontact	Copper alloy / Contact area: Au plating over Ni Terminal area: Au flash plating over Ni (Note) Pin contact and ground contact in common					

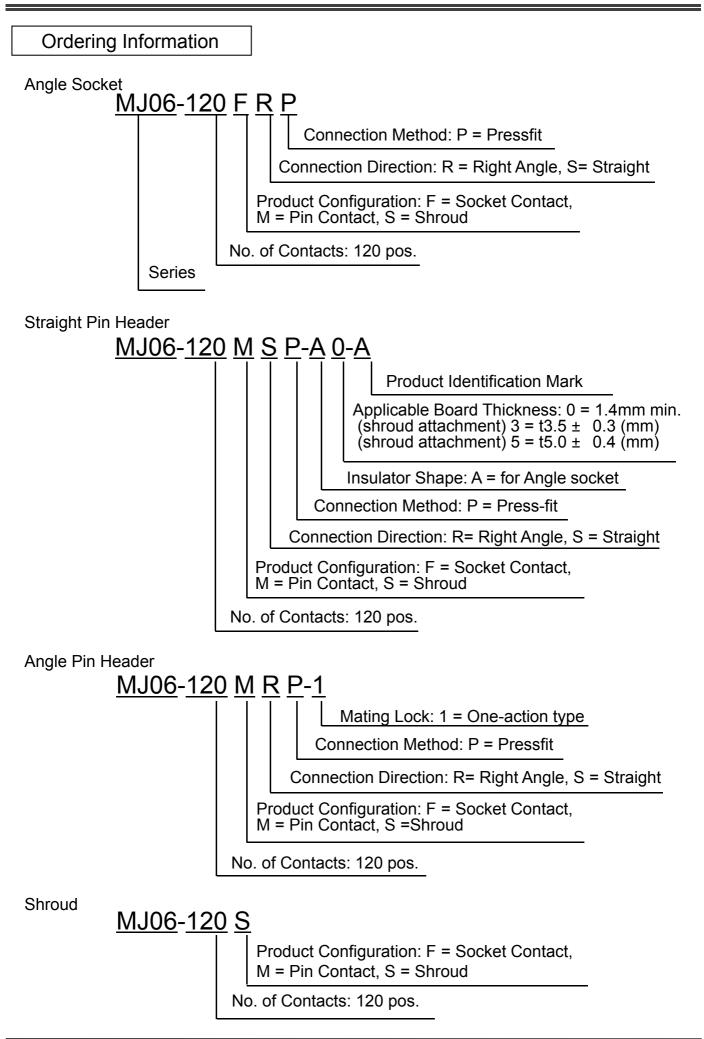
Socket Connector

Component	Material / Finish	
Insulator	Glass filled PBT (white)	
Contact	Copper alloy / Contact area: Au plating over Ni Terminal area: Au flash plating over Ni (Note) Socket contact and ground plate in common	

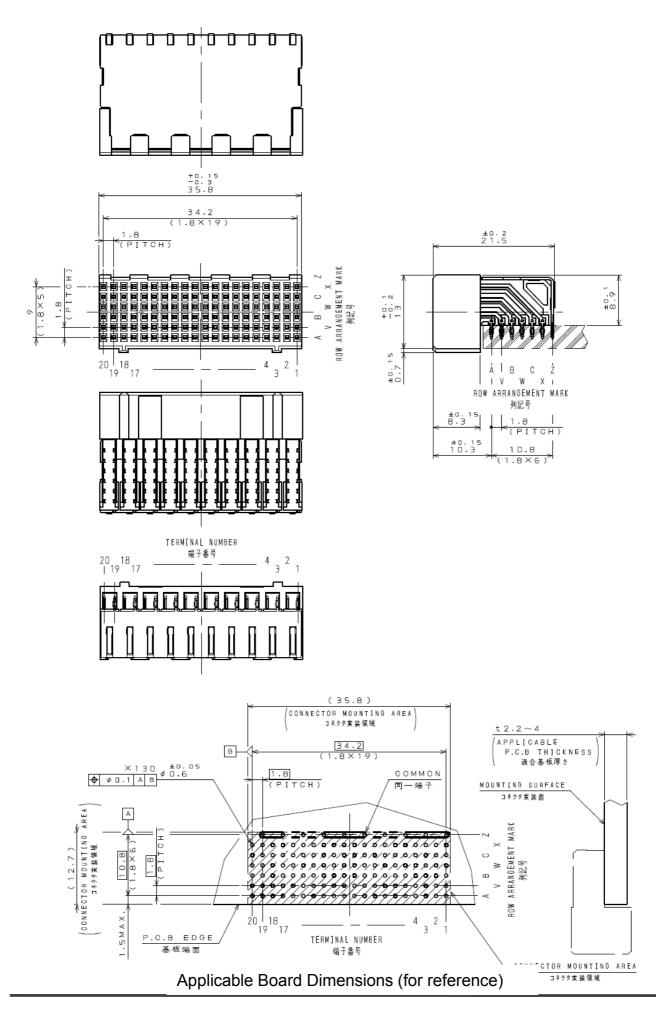
Board Through-Hole Specification (for reference)

Board Material	Glass fabric filled laminated epoxy board	
Board Thickness	1.4mm to 5.0mm	
Finished Diameter (Au flash plating over copper)	0.6mm dia. ± 0.05mm	
Copper Plating Thickness	20 µm (min.)	
Prepared Hole Drilled Diameter	0.7mm dia. ± 0.025mm	

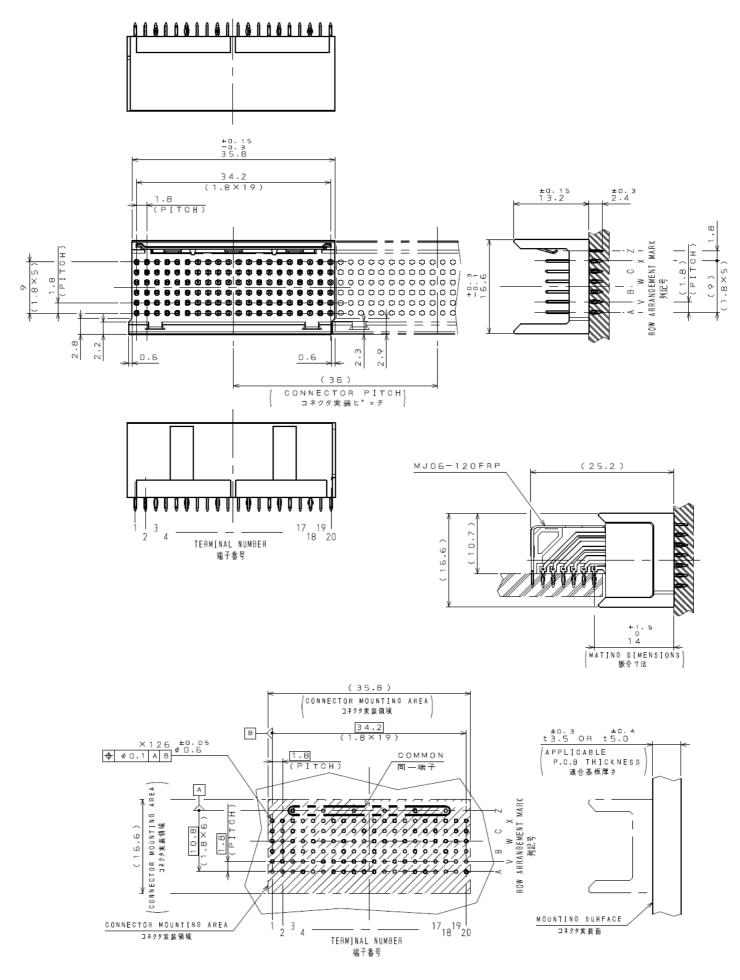
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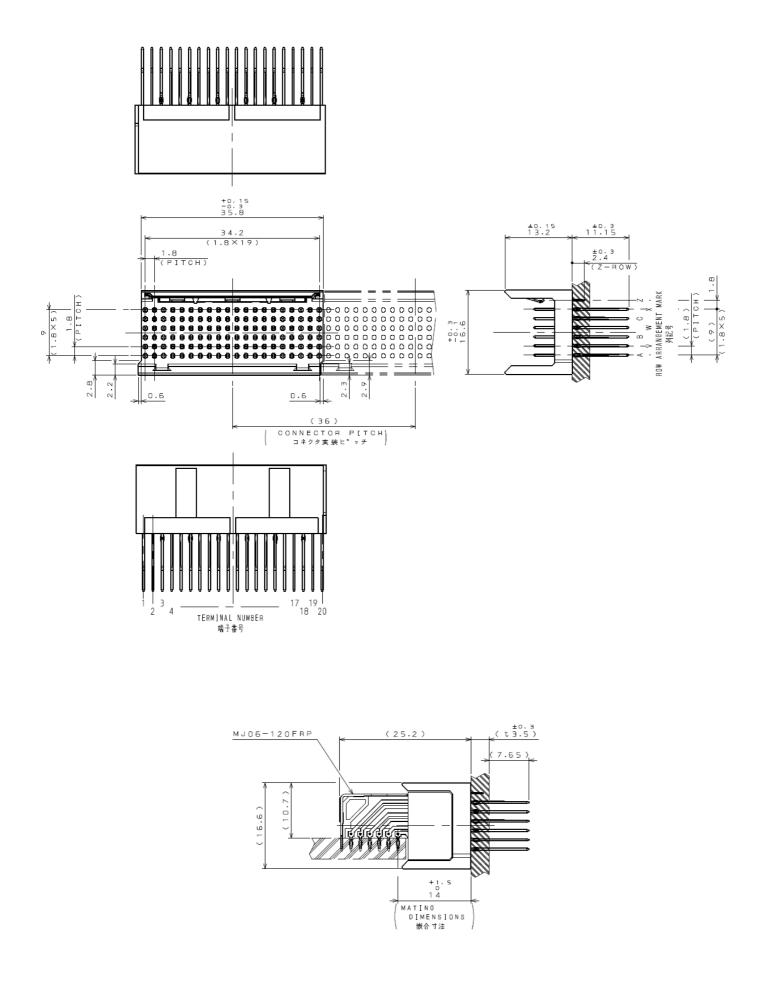
MJ06-120FRP (Angle Socket)



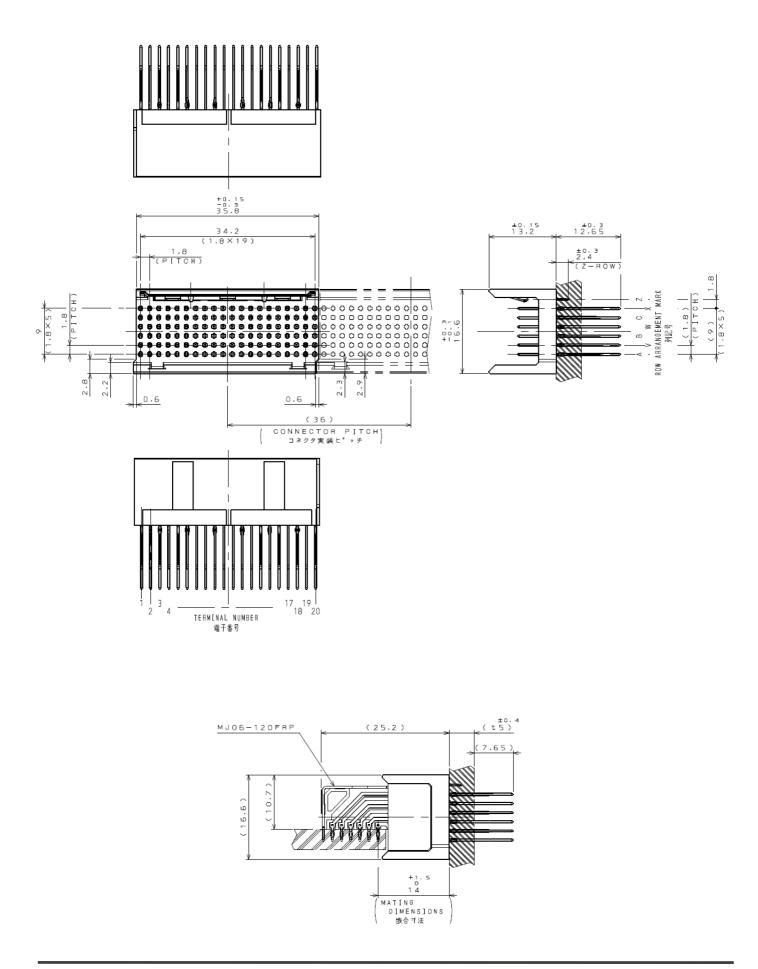
MJ06-120MSP-A0-A (Pin Header Short)



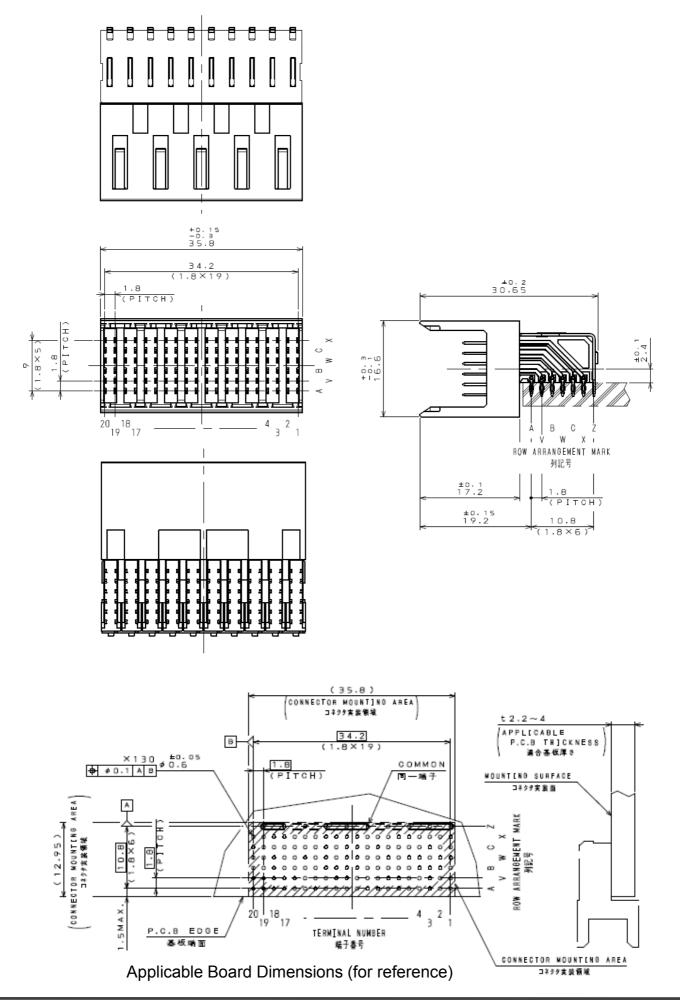
MJ06-120MSP-A3-A (Pin Header Long)



MJ06-120MSP-A5-A (Pin Header Long)

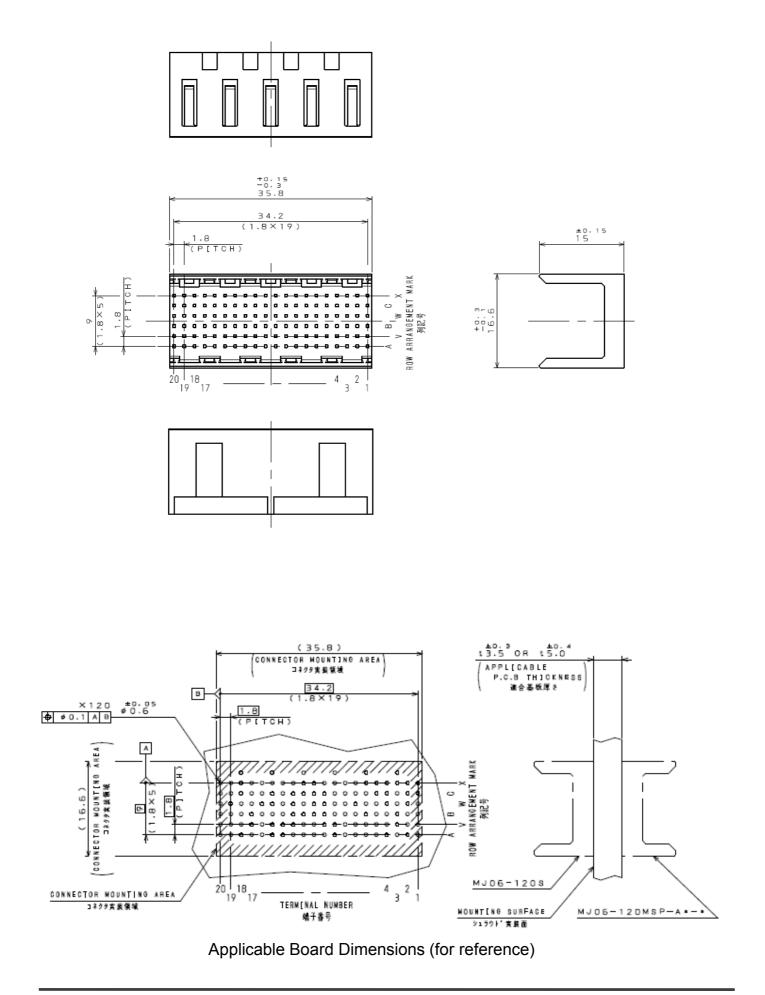


MJ06-120MRP-1 (Angle Pin Header)



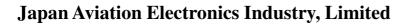
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MJ06-120S (Shroud)



SJ Drawing

Configuration	Part Number	SJ Drawing No.	Specification
Angle Socket	MJ06-120FRP	SJ108443	JACS-10524
Straight	MJ06-120MSP-A0-A	SJ108444	
Pin Header	MJ06-120MSP-A3-A	SJ108446	
	MJ06-120MSP-A5-A	SJ108447	
Angle Pin Header	MJ06-120MRP-1	SJ108452	
Shroud	MJ06-120S	SJ108448	



Notice: Products shown in this leaflet are made for the applications listed below. However, if the above-mentioned products are to be used in aerospace devices, marine cable-connection devices, atomic power control systems, medical equipment for life-support systems, or any other specific application requiring extremely high reliability, please contact JAE for further information. Recommended applications: computers, office machines, measuring devices, telecommunication devices (terminals, mobile devices), AV devices, household applications, FA devices, etc.

^{*} The specifications in this brochure are subject to change without notice. Please contact JAE for information. 10/10 JAE PMK Div. Proprietary. Copyright © 2010. Japan Aviation Electronics Industry. Ltd.